

Linear IC General purpose Converter

CMOS

D/A Converter for Digital Tuning (8 channels. 8-bit, with OP amplifier)

MB88347

■ DESCRIPTION

The MB88347 features 8 channels of 8-bit D/A converters (with output amplifiers). The output amplifier provides high current drive capability. As data is input via a serial link, only three control lines are required, and cascaded connections can be used.

The MB88347 is suitable for electronic volumes and replacement for potentiometers for adjustment, in addition to normal D/A converter applications.

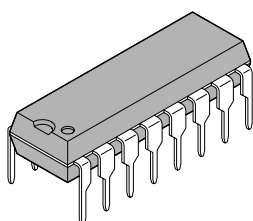
■ FEATURES

- Low power consumption (2 mW/ch)
- Small package
- Integrating 8 channels of R-2R type 8-bit D/A converter.

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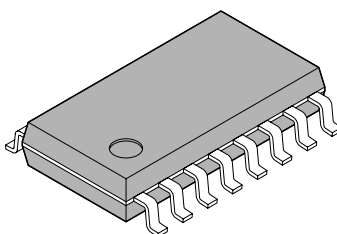
■ PACKAGES

16-pin plastic DIP



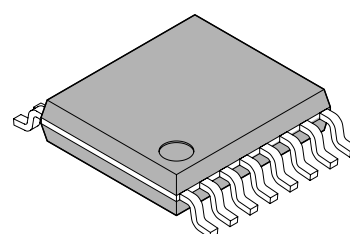
(DIP-16P-M04)

16-pin plastic SOP



(FPT-16P-M06)

16-pin plastic SSOP

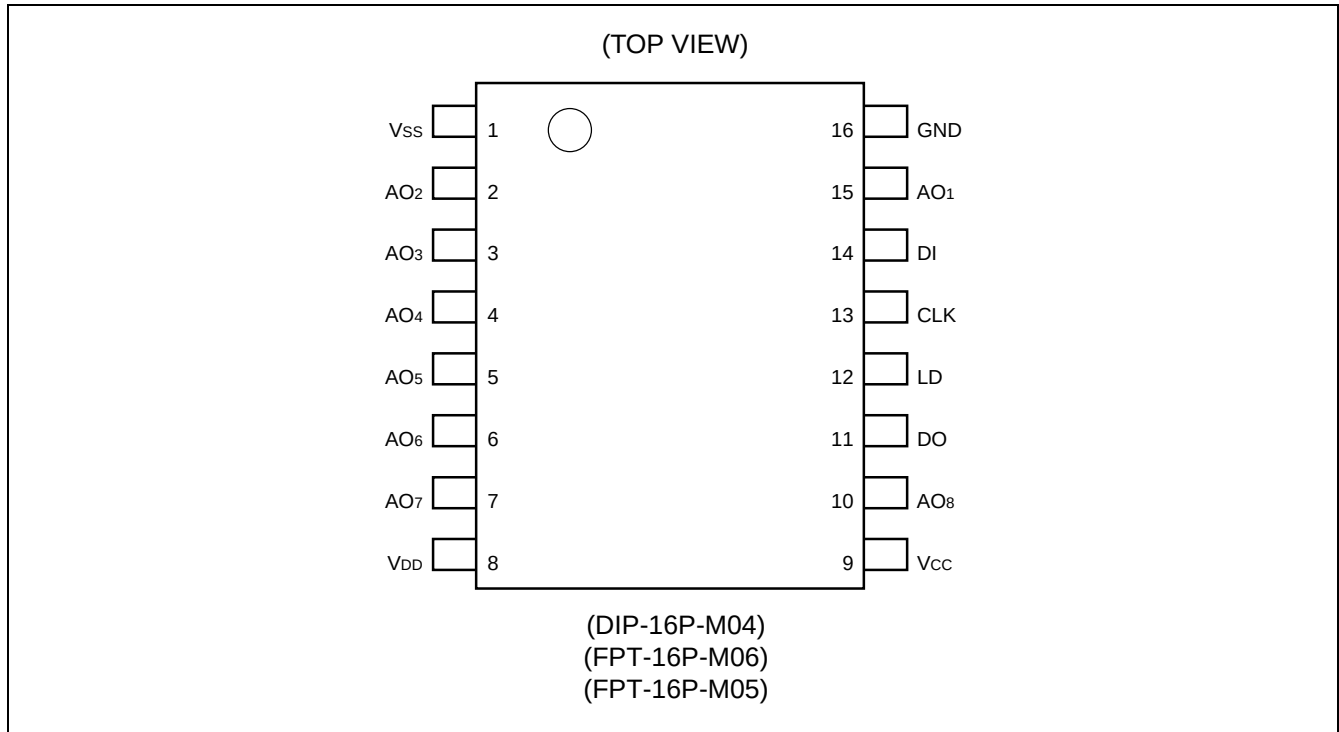


(FPT-16P-M05)

(Continued)

- Built-in analog output amplifier (Max +1.0 mA sink/source current)
- Analog output range : 0 to V_{CC}
- The range of D/A conversion can be independently set by separated the power supply for MCU interface and OP amplifier and the power supply for D/A converter.
- Capable of being controlled directly by a 3-V MCU (input voltage : “H” = $0.5 V_{CC}$, “L” = $0.2 V_{CC}$)
- Serial data input, 2.5 MHz operation
- CMOS process
- Package lineup : DIP 16-pin, SOP 16-pin, SSOP 16-pin

PIN ASSIGNMENT

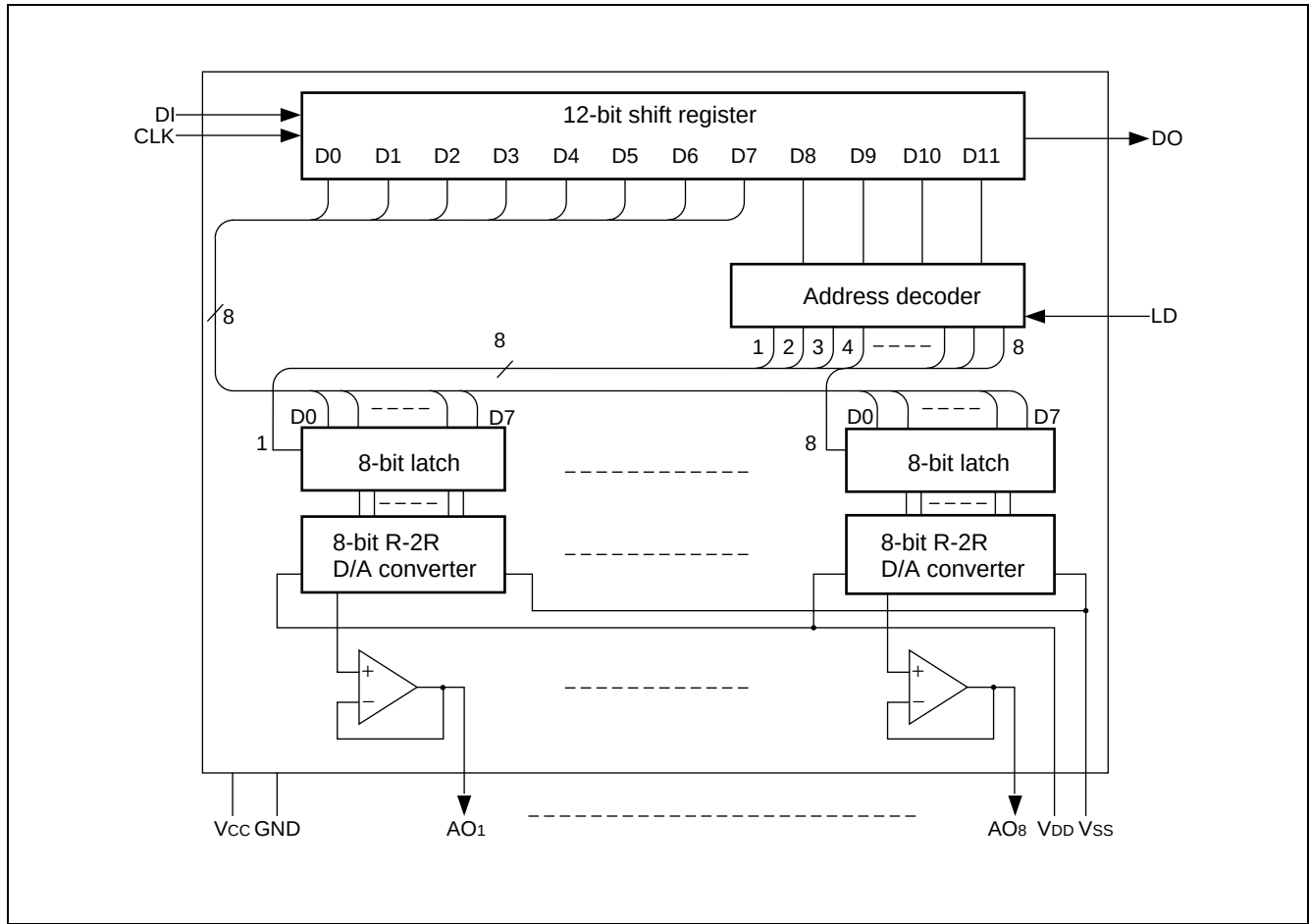


PIN DESCRIPTION

Pin No.	Symbol	I/O	Pin name	Function
14	DI*	I	Data input pin	Serial data input pin. This pin inputs 12-bit length serial data.
11	DO	O	Data output pin	This pin outputs MSB bit data of 12-bit shift register.
13	CLK*	I	Shift clock input pin	Shift clock input pin. The input signal from the DI pin is inputted to a 12-bit shift register on the rising edge of the shift clock.
12	LD*	I	Load signal input pin	If input "H" level to LD pin, the data of shift register is loaded to the decoder and the register for D/A output.
15 2 3 4 5 6 7 10	AO ₁ AO ₂ AO ₃ AO ₄ AO ₅ AO ₆ AO ₇ AO ₈	O	D/A output pin	These pins are 8-bit D/A output with OP amplifier.
9	V _{CC}	—	Power supply pin	Power supply pin of MCU interface and OP amplifier
16	GND	—	Ground pin	Ground pin of MCU interface and OP amplifier
8	V _{DD}	—	Power supply pin	Power supply pin of D/A converter
1	V _{SS}	—	Ground pin	Ground pin of D/A converter

* : DI, CLK, and LD pins are fixed to "L" level at non transfer.

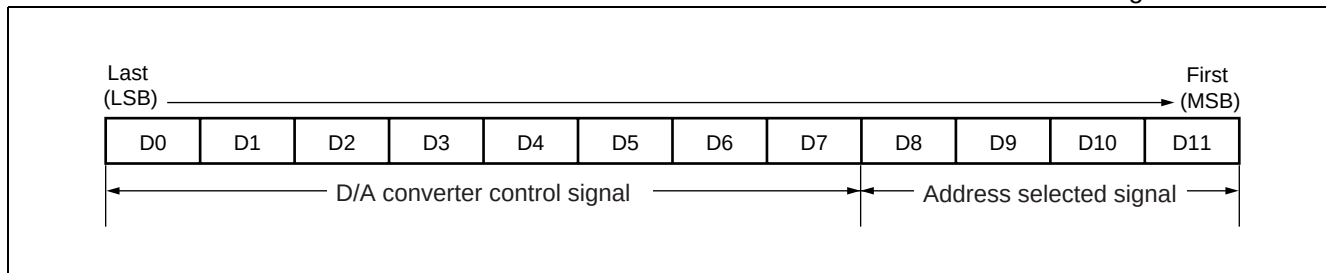
■ BLOCK DIAGRAM



■ DATA FOR CHIP CONTROL

1. Data for Shift Register

- MB88347 has 12-bit shift register for chip control.
- It is necessary to set the data as following configuration to 12-bit shift register.
- The data consists of 12 bits: a 4-bit address selection and an 8-bit D/A converter control signal.



2. D/A Converter Control Signal

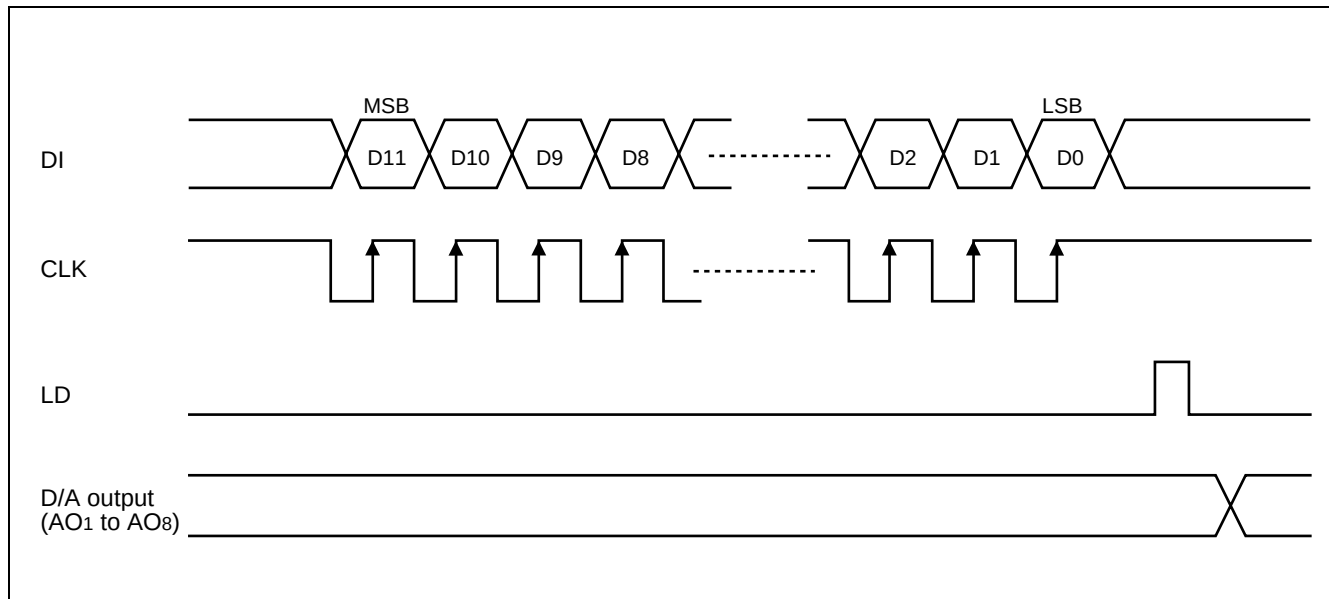
Input data signal								D/A converter output voltage
D0	D1	D2	D3	D4	D5	D6	D7	
0	0	0	0	0	0	0	0	$\doteq V_{SS}$
1	0	0	0	0	0	0	0	$\doteq V_{LB} + V_{SS}$
0	1	0	0	0	0	0	0	$\doteq V_{LB} \times 2 + V_{SS}$
}	}	}	}	}	}	}	}	}
0	1	1	1	1	1	1	1	$\doteq V_{LB} \times 254 + V_{SS}$
1	1	1	1	1	1	1	1	$\doteq V_{DD}$

$$V_{LB} = (V_{DD} - V_{SS}) / 255$$

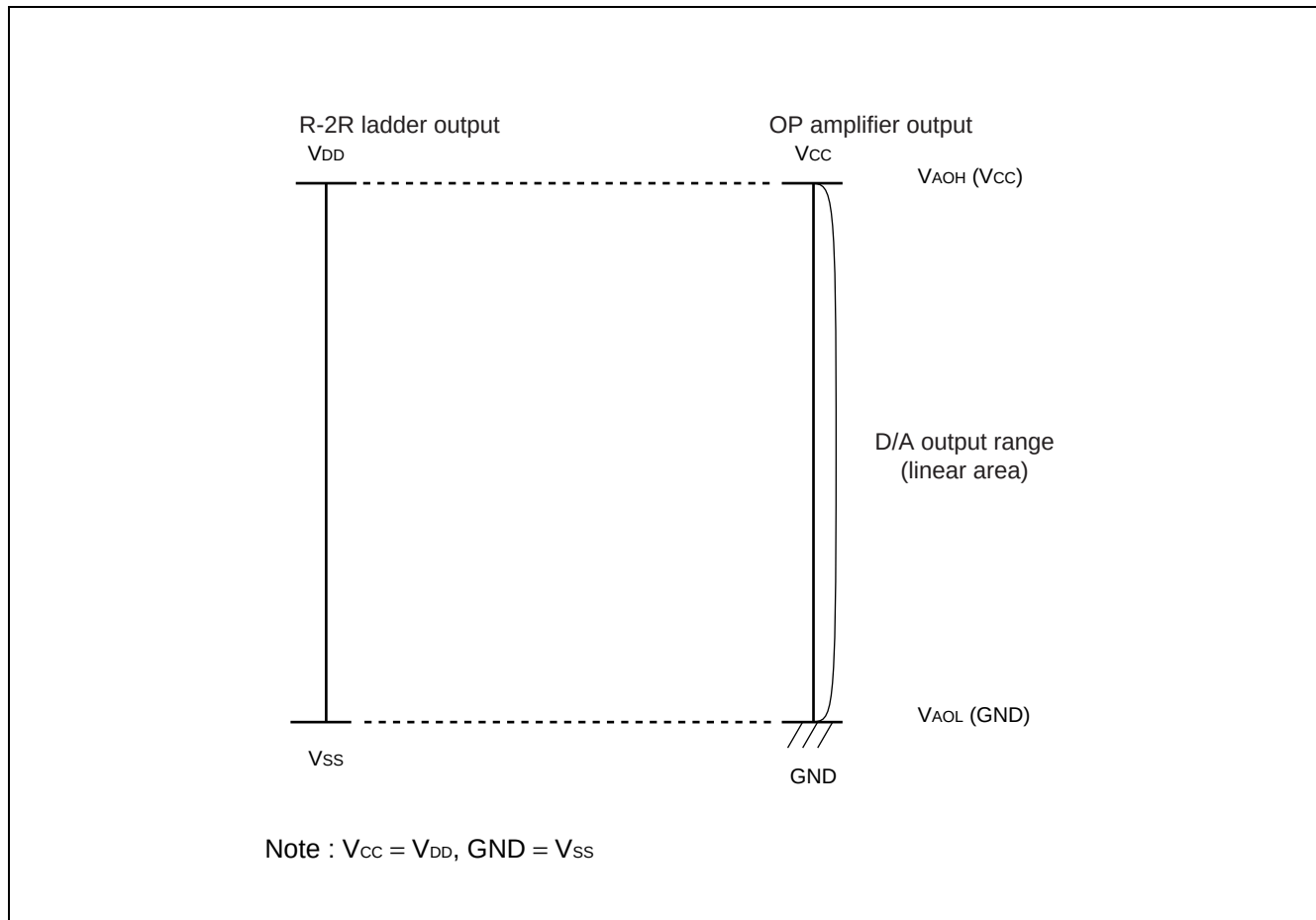
3. Address Selected Signal

Input data signal				Address selected
D8	D9	D10	D11	
0	0	0	0	Don't Care
0	0	0	1	AO ₁ selected
0	0	1	0	AO ₂ selected
0	0	1	1	AO ₃ selected
0	1	0	0	AO ₄ selected
0	1	0	1	AO ₅ selected
0	1	1	0	AO ₆ selected
0	1	1	1	AO ₇ selected
1	0	0	0	AO ₈ selected
1	0	0	1	Don't Care
1	0	1	0	Don't Care
1	0	1	1	Don't Care
1	1	0	0	Don't Care
1	1	0	1	Don't Care
1	1	1	0	Don't Care
1	1	1	1	Don't Care

■ TIMING CHART AT DATA SETTING



■ ANALOG OUTPUT VOLTAGE RANGE



■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating		Unit
			Min	Max	
Power supply voltage	V _{CC}	The case that GND is referred. Ta = +25 °C	− 0.3	+ 7.0	V
	V _{DD}		− 0.3*	+ 7.0*	V
Input voltage	V _{IN}		− 0.3	V _{CC} + 0.3	V
Output voltage	V _{OUT}		− 0.3	V _{CC} + 0.3	V
Power consumption	P _D	—	—	250	mW
Operating temperature	Ta	—	− 40	+ 85	°C
Storage temperature	Tstg	—	− 55	+ 150	°C

* : V_{CC} ≥ V_{DD}

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	Value		Unit
			Min	Max	
Power supply Voltage 1	V _{CC}	—	4.5	5.5	V
	GND	—	—	0	V
Power supply Voltage 2	V _{DD}	V _{DD} − V _{SS} ≥ 2.0 V	2.0	V _{CC}	V
	V _{SS}		GND	V _{CC} − 2.0	V
Analog output source current	I _{AL}	—	—	1.0	mA
Analog output sink current	I _{AH}	—	—	1.0	mA
Oscillation limited output capacitance	C _{OL}	—	—	1.0	μF
Digital data setting range	—	—	#00	#FF	—
Operating temperature	Ta	—	− 40	+ 85	°C

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

■ ELECTRICAL CHARACTERISTICS

1. DC Characteristics

(1) Digital block

($V_{DD}, V_{CC} = +5\text{ V} \pm 10\%$ ($V_{CC} \geq V_{DD}$), $GND, V_{SS} = 0\text{ V}$, $T_a = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$)

Parameter	Symbol	Pin name	Conditions	Value			Unit
				Min	Typ	Max	
Power supply voltage	V _{CC}	V _{CC}	—	4.5	5.0	5.5	V
Power supply current	I _{CC}		At CLK = 1 MHz operating (at no load) At Ta = − 20 °C to + 85 °C	—	0.8	1.8	mA
			At CLK = 1 MHz operating (at no load) At Ta = − 40 °C to + 85 °C	—	0.8	2.1	
Input leakage current	I _{ILK}	CLK DI LD	V _{IN} = 0 to V _{CC}	−10	—	10	μA
“L” level input voltage	V _{IL}		—	—	—	0.2 V _{CC}	V
“H” level input voltage	V _{IH}		—	0.5 V _{CC}	—	—	V
“L” level output voltage	V _{OL}	DO	I _{OL} = 2.5 mA	—	—	0.4	V
“H” level output voltage	V _{OH}		I _{OH} = − 400 μA	V _{CC} − 0.4	—	—	V

Note : I_{OL} and I_{OH} are output load current.

(2) Analog block

($V_{DD}, V_{CC} = +5\text{ V} \pm 10\%$ ($V_{CC} \geq V_{DD}$), $GND, V_{SS} = 0\text{ V}$, $T_a = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$)

Parameter	Symbol	Pin name	Conditions	Value			Unit
				Min	Typ	Max	
Consumption current	I_{DD}	V_{DD}	No load	—	1.0	1.5	mA
Analog power supply voltage	V_{DD}	V_{DD}	$V_{DD} - V_{SS} \geq 2.0\text{ V}$	2.0	—	V_{CC}	V
	V_{SS}	V_{SS}		GND	—	$V_{CC} - 2.0$	V
Resolution	Res	AO ₁ to AO ₈	—	—	8	—	bit
Monotonic increase	Rem		No load $V_{DD} \leq V_{CC} - 0.1\text{ V}$ $V_{SS} \geq 0.1\text{ V}$	—	8	—	bit
Non linearity error*1	LE			−1.5	—	1.5	LSB
Differential linearity error*2	D_{LE}			−1.0	—	1.0	LSB
Output minimum voltage 1	V_{AOL1}	AO ₁ to AO ₈	$V_{DD} = V_{CC}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AL} = 0\text{ }\mu\text{A}$ Digital data = #00	V_{SS}	—	$V_{SS} + 0.1$	V
Output minimum voltage 2	V_{AOL2}		$V_{DD} = V_{CC} = 5.0\text{ V}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AL} = 500\text{ }\mu\text{A}$ Digital data = #00	$V_{SS} - 0.2$	V_{SS}	$V_{SS} + 0.2$	V
Output minimum voltage 3	V_{AOL3}		$V_{DD} = V_{CC} = 5.0\text{ V}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AH} = 500\text{ }\mu\text{A}$ Digital data = #00	V_{SS}	—	$V_{SS} + 0.2$	V
Output minimum voltage 4	V_{AOL4}		$V_{DD} = V_{CC} = 5.0\text{ V}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AL} = 1.0\text{ mA}$ Digital data = #00	$V_{SS} - 0.3$	V_{SS}	$V_{SS} + 0.3$	V
Output minimum voltage 5	V_{AOL5}		$V_{DD} = V_{CC} = 5.0\text{ V}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AH} = 1.0\text{ mA}$ Digital data = #00	V_{SS}	—	$V_{SS} + 0.3$	V

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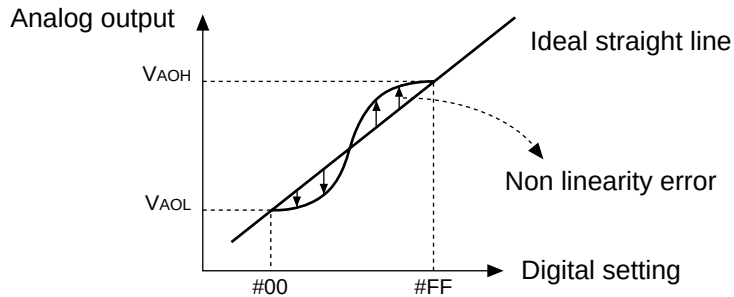
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($V_{DD}, V_{CC} = +5\text{ V} \pm 10\%$ ($V_{CC} \geq V_{DD}$), $GND, V_{SS} = 0\text{ V}$, $T_a = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$)

Parameter	Symbol	Pin name	Conditions	Value			Unit
				Min	Typ	Max	
Output maximum voltage 1	V_{AOH1}	AO ₁ to AO ₈	$V_{DD} = V_{CC}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AL} = 0\text{ }\mu\text{A}$ Digital data = #FF	$V_{DD} - 0.1$	—	V_{DD}	V
Output maximum voltage 2	V_{AOH2}		$V_{DD} = V_{CC} = 5.0\text{ V}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AL} = 500\text{ }\mu\text{A}$ Digital data = #FF	$V_{DD} - 0.2$	—	V_{DD}	V
Output maximum voltage 3	V_{AOH3}		$V_{DD} = V_{CC} = 5.0\text{ V}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AH} = 500\text{ }\mu\text{A}$ Digital data = #FF	$V_{DD} - 0.2$	V_{DD}	$V_{DD} + 0.2$	V
Output maximum voltage 4	V_{AOH4}		$V_{DD} = V_{CC} = 5.0\text{ V}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AL} = 1.0\text{ mA}$ Digital data = #FF	$V_{DD} - 0.3$	—	V_{DD}	V
Output maximum voltage 5	V_{AOH5}		$V_{DD} = V_{CC} = 5.0\text{ V}$ $V_{SS} = GND = 0.0\text{ V}$ $I_{AH} = 1.0\text{ mA}$ Digital data = #FF	$V_{DD} - 0.3$	V_{DD}	$V_{DD} + 0.3$	V

*1 : Non linearity error : The error of the I/O curve from the ideal straight line between output voltages at "00" and "FF".

*2 : Differential linearity error : The error from the ideal increment given when the digital value is incremented by one bit.



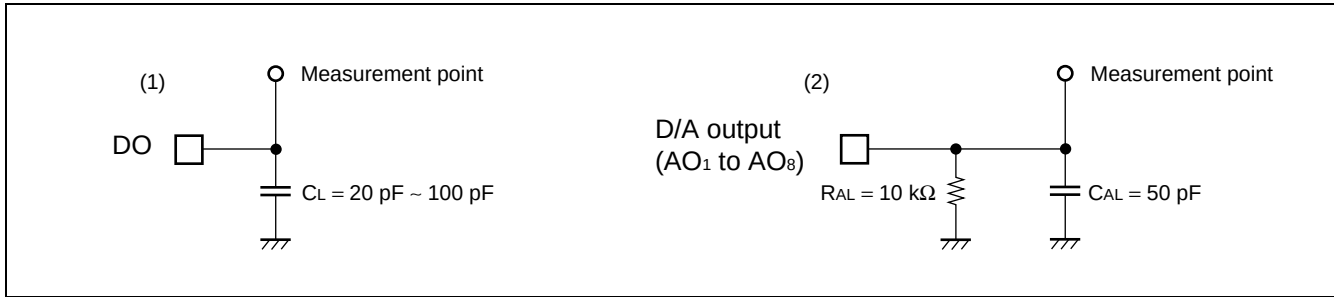
Note: V_{AOH} and V_{AOL} do not always match V_{DD} and V_{SS} , respectively.

2. AC Characteristics

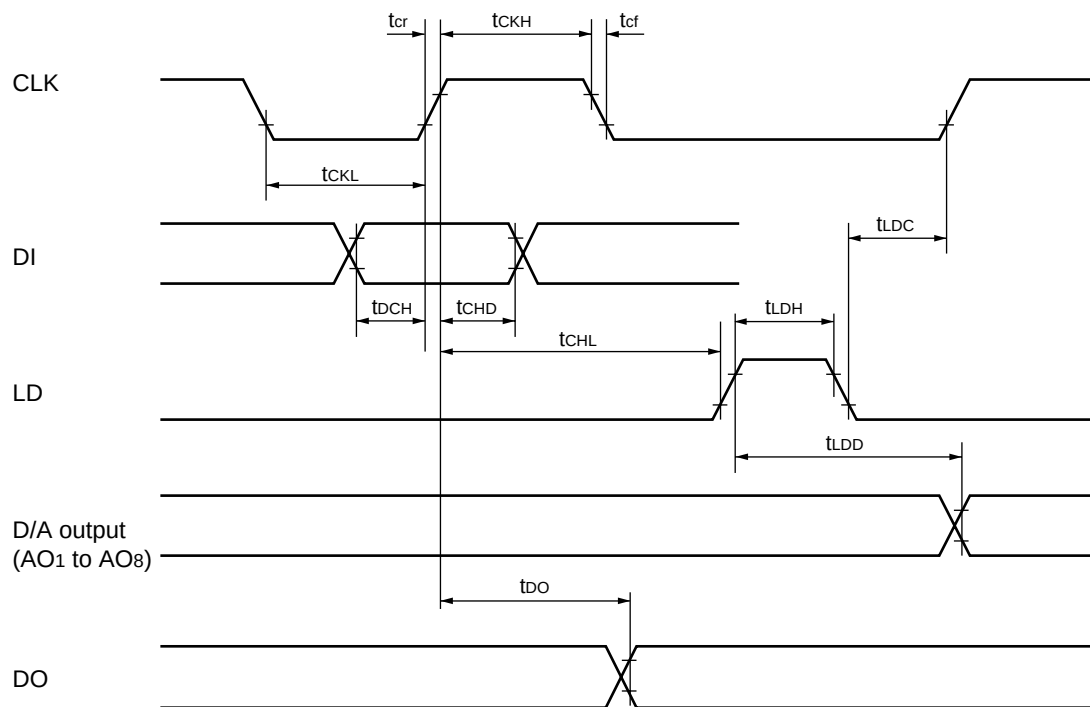
(V_{DD}, V_{CC} = + 5 V ± 10% (V_{CC} ≥ V_{DD}) , GND, V_{SS} = 0 V, Ta = - 40 °C to + 85 °C)

Parameter	Symbol	Conditions	Value		Unit
			Min	Max	
“L” level clock pulse width	t _{CKL}	—	200	—	ns
“H” level clock pulse width	t _{CKH}	—	200	—	ns
Clock rising time Clock falling time	t _{Cr} t _{Cf}	—	—	200	ns
Data setup time	t _{DCH}	—	30	—	ns
Data hold time	t _{CHD}	—	60	—	ns
Load setup time	t _{CHL}	—	200	—	ns
Load hold time	t _{LDC}	—	100	—	ns
“H” level load pulse width	t _{LDH}	—	100	—	ns
Data output delay time	t _{DO}	Refer to “Load condition (1) ”.	70	350	ns
D/A output settling time	t _{LDD}	Refer to “Load condition (2) ”.	—	100	μs

• Load condition

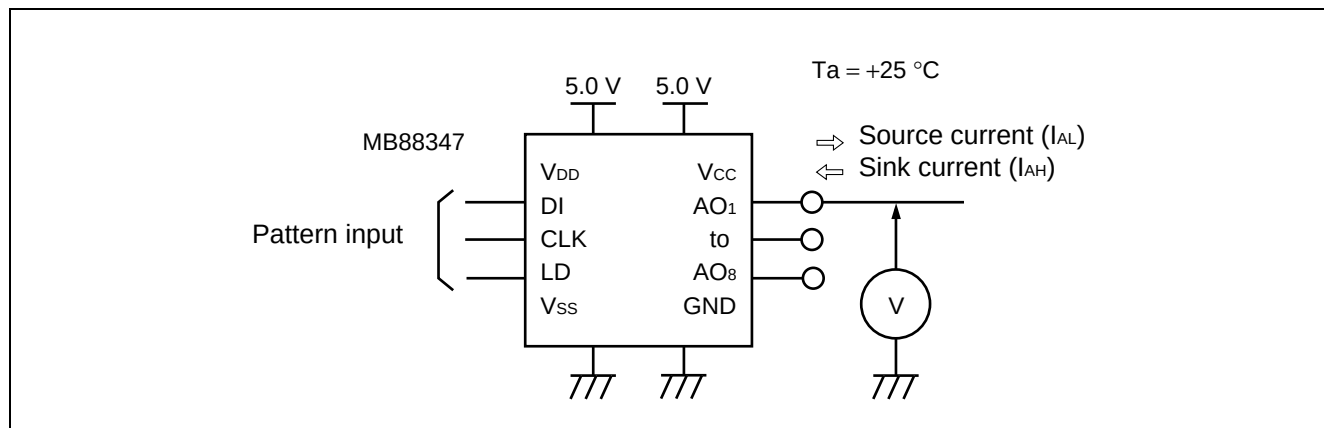


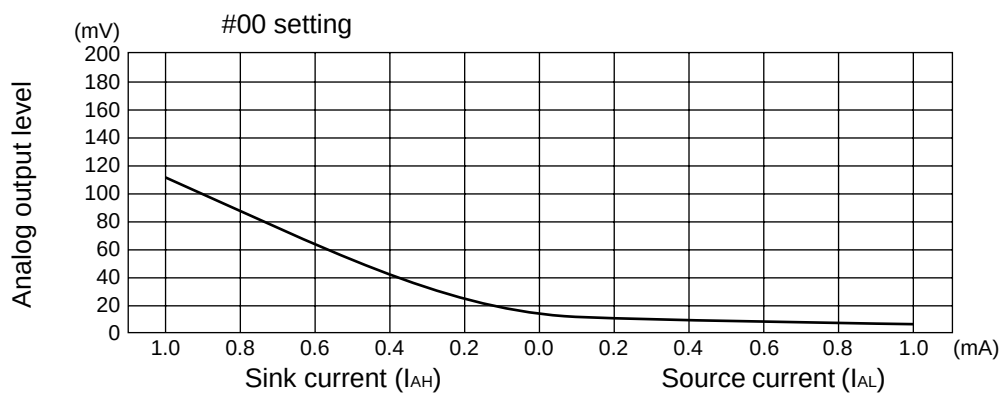
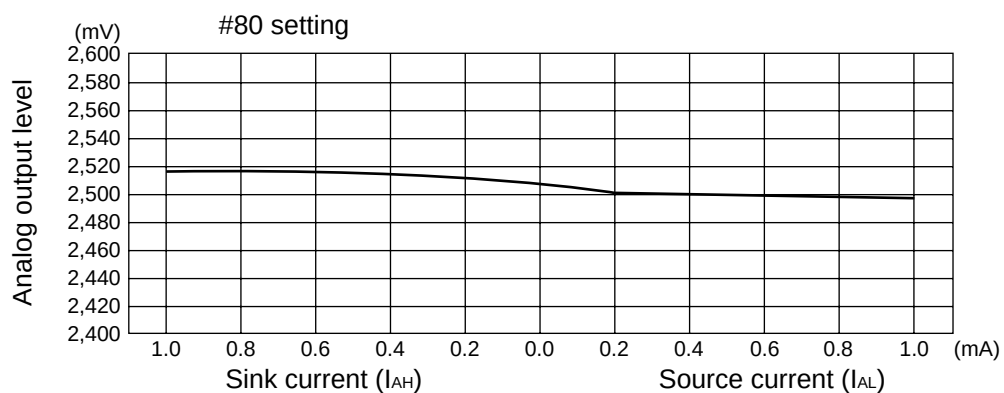
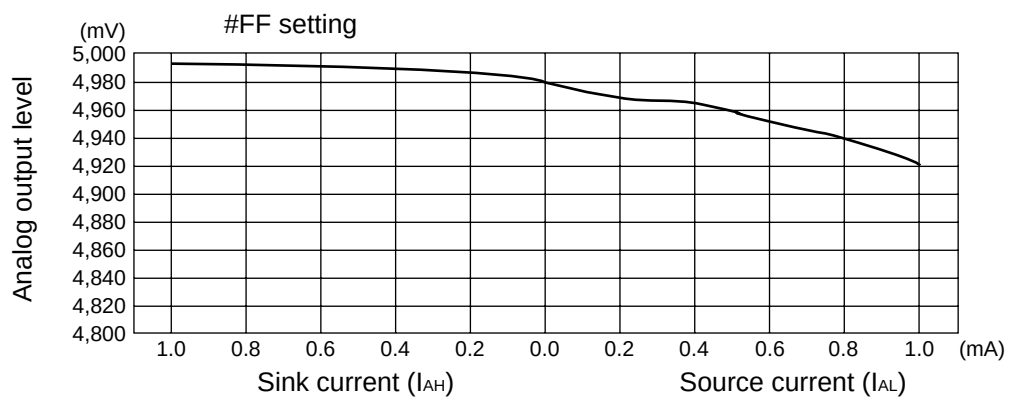
• Input/output timing



Note : The D/A output evaluation level is 90% and 10% of V_{CC} . The other evaluation level is 80% and 20% of V_{CC} .

■ EXAMPLE CHARACTERISTIC of $V_{AO} - I_{AO}$





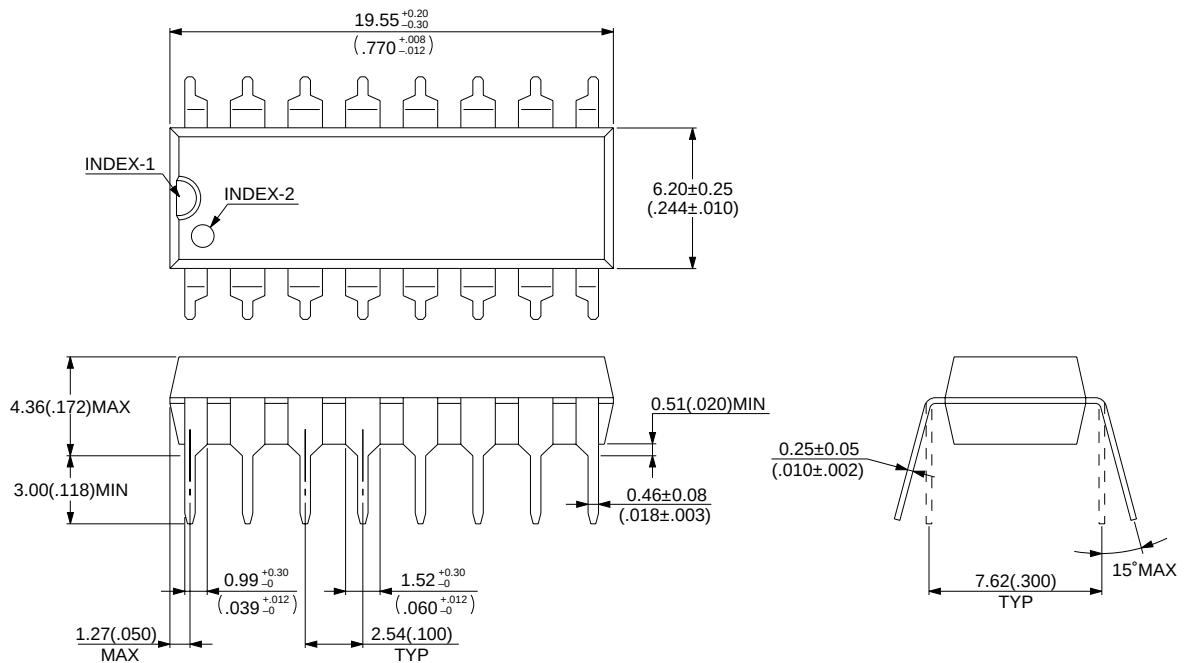
MB88347

■ ORDERING INFORMATION

Part No.	Package	Remarks
MB88347P	16-pin plastic DIP (DIP-16P-M04)	
MB88347PF	16-pin plastic SOP (FPT-16P-M06)	
MB88347PFV	16-pin plastic SSOP (FPT-16P-M05)	

■ PACKAGE DIMENSIONS

16-pin plastic DIP
(DIP-16P-M04)



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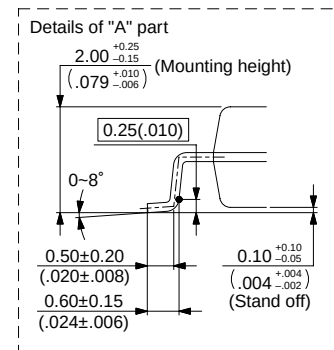
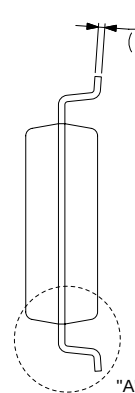
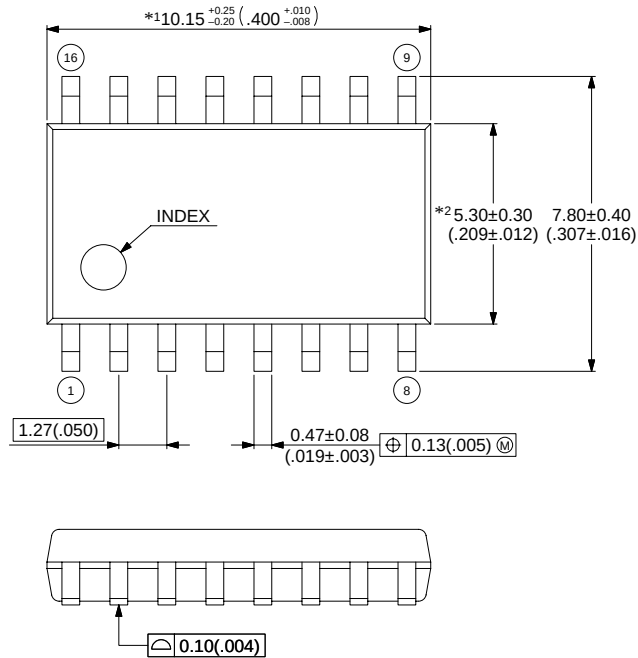
Dimensions in mm (inches).

Note : The values in parentheses are reference values.

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16-pin plastic SOP (FPT-16P-M06)

- Note 1) *1 : These dimensions include resin protrusion.
 Note 2) *2 : These dimensions do not include resin protrusion.
 Note 3) Pins width and pins thickness include plating thickness.
 Note 4) Pins width do not include tie bar cutting remainder.



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Dimensions in mm (inches).

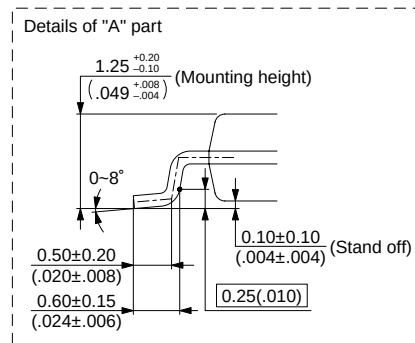
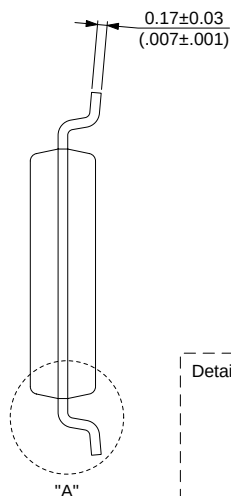
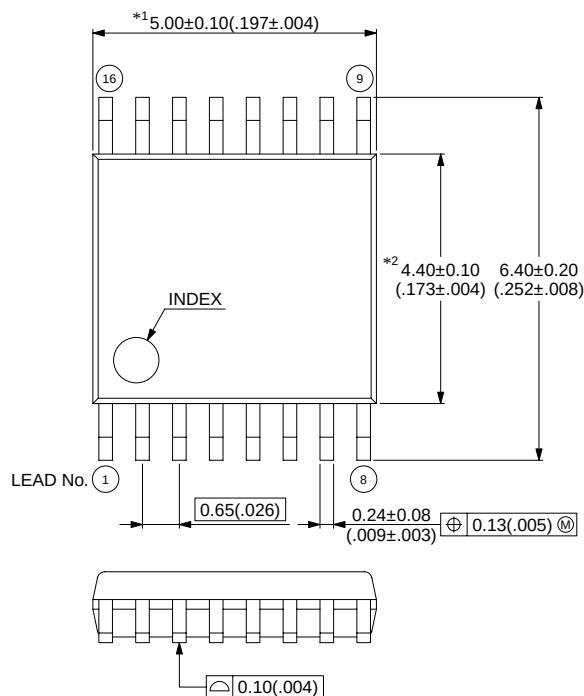
Note: The values in parentheses are reference values.

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16-pin plastic SSOP (FPT-16P-M05)

- Note 1) *1 : Resin protrusion. (Each side : +0.15 (.006) Max).
 Note 2) *2 : These dimensions do not include resin protrusion.
 Note 3) Pins width and pins thickness include plating thickness.
 Note 4) Pins width do not include tie bar cutting remainder.



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Dimensions in mm (inches).
 Note: The values in parentheses are reference values.

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